Claims

1. Manufactured item comprising a substrate (2) with an optoelectronic component (3), characterized by the fact
that the optoelectronic component (3) is contacted in a planar manner.

2. Manufactured item according to claim 1
characterized by the fact
that the substrate (2) has a conducting element (7), in particular a printed conductor, with which the optoelectronic element (3) is contacted in a planar manner.

3. Manufactured item according to one of the foregoing claims,
characterized by the fact
that the substrate (2) and/or the optoelectronic component (3) are at least partially provided with an insulating layer (5), on which a planar conducting structure (6) is disposed for planar contacting of the optoelectronic components (3).

4. Manufactured item according to claim 3,
characterized by the fact
that the insulating layer (5) is a foil, enamel, and/or a polymer layer.

5. Manufactured item according to claim 3 or 4,
characterized by the fact
that the insulating layer (5) is transparent in the area of a light exit and/or entry opening of the optoelectronic component (3).

6. Manufactured item according to claim 3 or 4,
characterized by the fact

that a window is opened in the insulating layer in the area of a light exit and/or entry opening of the optoelectronic component (3).

7. Manufactured item according to one of claims 3 to 6,
characterized by the fact
that in the insulating layer in the area of a contact point for the optoelectronic component (3) a window is opened through which the planar conducting structure is led to the contact point of the optoelectronic component.

8. Manufactured item according to one of claims 3 to 7,
characterized by the fact
that the insulating layer (5) contains pigments to color the light emitted from or absorbed by the optoelectronic component (3).

9. Manufactured item according to one of the foregoing claims,
characterized by the fact
that the planar contact at least partially covers a light exit and/or entry opening of the optoelectronic component.

10. Manufactured item according to one of the foregoing claims
characterized by the fact
that the optoelectronic component (3) is LED, in particular an OLED, and/or a photovoltaic component.

11. Manufactured item according to one of the foregoing claims
characterized by the fact
that the substrate (2) is a printed circuit board, a Flex, or a lead frame.

12. Manufactured item according to one of the foregoing claims,
characterized by the fact
that the height of the manufactured item (1) is less than 0.4 mm.

13. Process for the manufacture of a manufactured item (1) comprising a substrate (2) with an optoelectronic component (3),
characterized by the fact
that the optoelectronic component (3) is contacted in a planar manner.